

DATASHEET

SMD • Low Power LED 45-21/QK2C-B56704CADB41/2T



Features

- · PLCC-2 package
- Top view white LED
- High luminous intensity output
- · Wide viewing angle
- Pb-free
- RoHS compliant compliant version.
- Compliance with EU REACH.
- \bullet Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Description

The Everlight 45-21 package has high efficacy, high CRI, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- · General lighting
- · Decorative and Entertainment Lighting
- Indicators
- Illumination
- · Switch lights



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Pure White	Water Clear

Absolute Maximum Ratings (T_{Soldering}=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	I _F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Power Dissipation	Pd	110	mW
Electrostatic Discharge(HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +90	°C
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec. Hand Soldering: 350 °C for 3 sec.	

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics (T_{Soldering}=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	I _V	2200		3000	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA
Forward Voltage	V _F	2.9		3.4	V	I _F =20mA
Reverse Current	I _R			50	μA	V _R =5V
Color Rendering Index	Ra	75				I _F =20mA

Notes:

- 1. Tolerance of Luminous Intensity: ±11%.
- 2. Tolerance of Forward Voltage: ±0.05V.
- 3. Tolerance Color Rendering Index: ± 2



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
4C	2200	2400		
6C	2400	2600	_ 	1 =20m A
8C	2600	2800	- mcd -	I _F =20mA
AD	2800	3000		

Tolerance of Luminous Intensity: ±11%

Bin Range of Forward Voltage

Group	Bin Code	Min.	Max.	Unit	Condition		
	36	2.9	3.0				
	37	3.0	3.1	_			
B41	38	3.1	3.2	V	I _F =20mA		
	39	3.2	3.3	_	·		
	40	3.3	3.4				
Note: Tolerance of Forward Voltage: ±0.05V.							



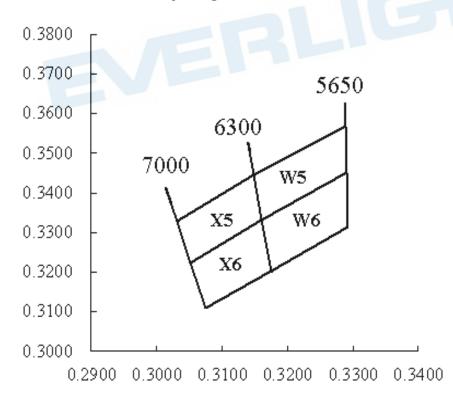
Bin Range of Chromaticity Coordinates

ССТ	Bin Code	CIE_x	CIE_y	ССТ	Bin Code	CIE_x	CIE_y
	X5	0.3031	0.3327	5650K ~6300K	W5 W6	0.3148	0.3444
		0.3148	0.3444			0.3288	0.3569
		0.3160	0.3332			0.3290	0.3451
7000K		0.3052	0.3224			0.3160	0.3332
~6300K	X6	0.3052	0.3224			0.3160	0.3332
		0.3160	0.3332			0.3290	0.3451
		0.3175	0.3204			0.3292	0.3313
		0.3076	0.3108			0.3175	0.3204

Note:

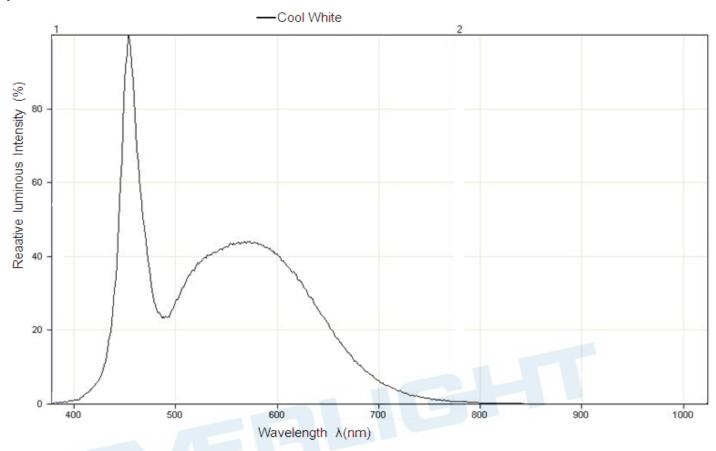
- 1. The value is based on driving current by 20mA.
- 2. Tolerance of Chromaticity Coordinates: ±0.01

The C.I.E. 1931 Chromaticity Diagram





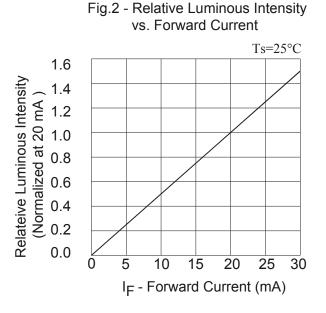
Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 - Forward Voltage Shift vs.

Junction Temperature 0.20 0.15 Forward Voltage Shift -V 0.10 0.05 0.00 -0.05 -0.10 -0.15 -0.20 -25 0 25 50 75 -50 100 Tj - Junction Temperature (°C)



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Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

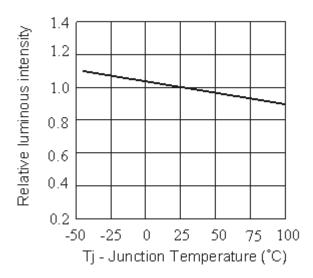


Fig.5 - Max. Driving Forward Current vs. Soldering Temperature

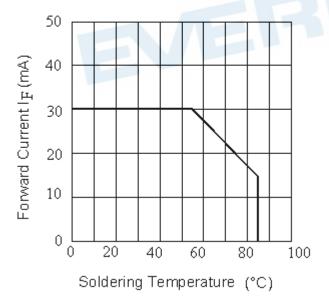


Fig.4 - Forward Current vs. Forward Voltage

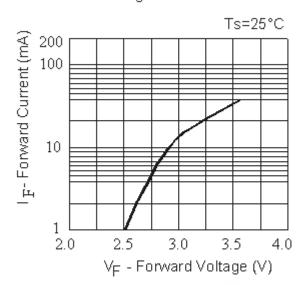
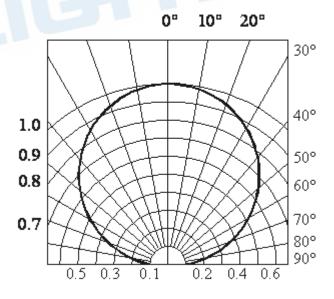
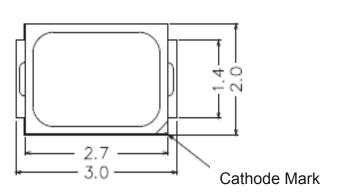


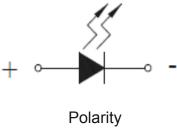
Fig.6 - Radiation Diagram

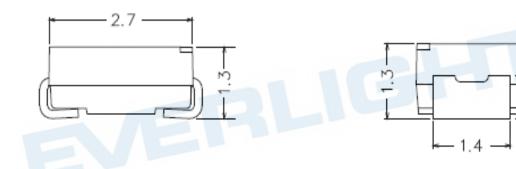


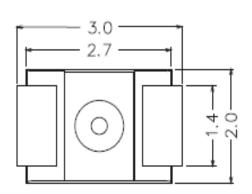


Package Dimension









4.3

Recommended Solder Pad

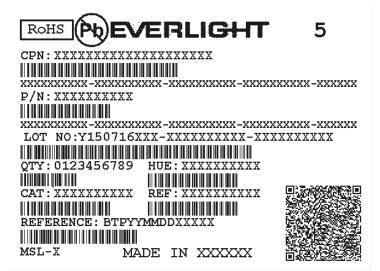
Note:

Tolerance unless mentioned is ±0.2mm; Unit = mm



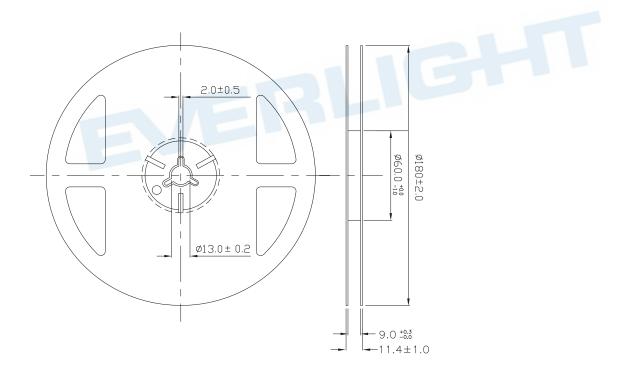
Moisture Resistant Packing Materials

Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- · HUE: Chromaticity Coordinates
- · REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions

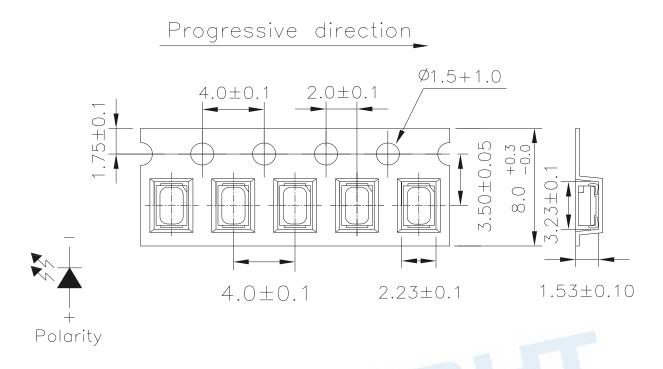


Note:

Tolerances unless mentioned ±0.1mm. Unit = mm



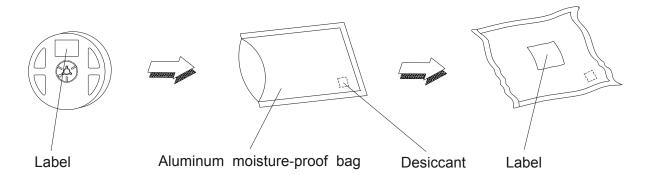
Carrier Tape Dimensions: Loaded Quantity 250/500/1000/2000 pcs Per Reel



Note:

Tolerance unless mentioned is ±0.1mm; Unit = mm

Moisture Resistant Packing Process





Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp.: 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85°C,85%RH, I _F = 15 mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85°C	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40°C, I _F = 30 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25°C, I _F = 30 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55°C, I _F =30 mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85°C, I _F = 15 mA	1000 Hrs.	22 PCS.	0/1



Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

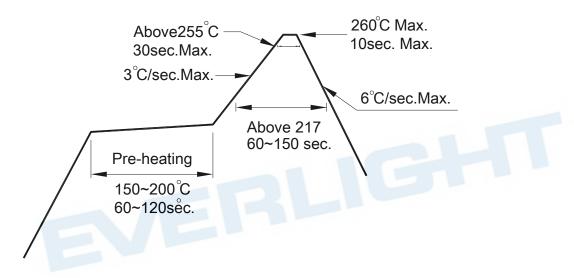
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

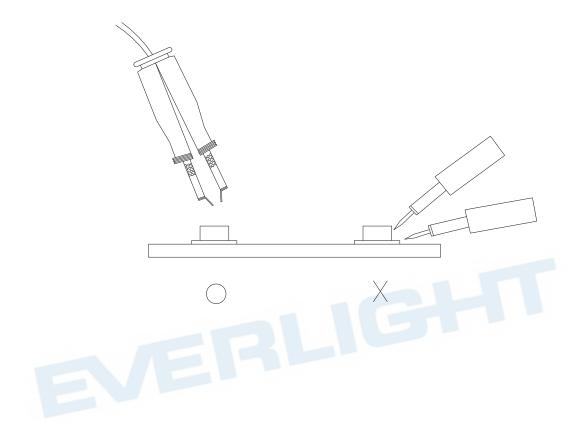


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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